



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Won Sun Shin, DoSung Chun, SangHo Lee, SeonGoo Lee, Vincent DiCaprio

Assignee: Amkor Technology, Inc.

Title: Semiconductor Package And Method For Fabricating The Same

Serial No.: 09/574,541 Filing Date: May 19, 2000

Examiner: C. Luu Group Art Unit: 2825

Batch No.: M03 Date Allowed: 9/17/01

Docket No.: AB-975 US

#13/A
AMW
4-4-02

San Jose, California
December 3, 2001

BOX ISSUE FEE
COMMISSIONER FOR PATENTS
Washington, D. C. 20231

**AMENDMENT AFTER ALLOWANCE
PURSUANT TO 37 C.F.R. §1.312**

Dear Sir:

Pursuant to 37 C.F.R. § 1.312 and co-incident with the payment of the issue fee,
Applicants respectfully request the entrance of an amendment to the specification.

IN THE SPECIFICATION

Please replace the paragraph beginning at page 25, line 6 with the following rewritten paragraph. Attached hereto is a marked-up version of the changes made to the specification by the current amendment. The attached page is captioned "**Version with markings to show changes made.**"

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Other embodiments of semiconductor packages and methods of making them are disclosed in U.S. Patent Application Serial Number 09/566,069, which was filed with the U.S. Patent and Trademark Office on May 5, 2000, and in U.S. Patent Application Serial Number

824335 v1 / PF-OA [Rev. 000913]

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